TE Internal #: 5-2337939-3

Board-to-Board, 98 Position, 1 mm [.039 in] Centerline, Vertical,

Black, Signal, -40 – 85 °C, PCI & PCI Express Connectors

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Connectors > PCB Connectors > Card Edge Connectors > PCI & PCI Express Connectors



Connector System: Board-to-Board

Number of Positions: 98

PCI Generation: 4

Centerline (Pitch): 1 mm [.039 in]

Contact Mating Area Plating Material Thickness: [30 µin]

Features

Product Type Features

| Connector & Contact Terminates To | Printed Circuit Board |
|---|-----------------------|
| Connector System | Board-to-Board |
| Sealable | No |
| Configuration Features | |
| Number of Positions | 98 |
| PCB Mount Orientation | Vertical |
| Ejector | Without |
| Body Features | |
| Primary Product Color | Black |
| Contact Features | |
| Contact Mating Area Plating Material | Gold |
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Copper Alloy |
| | |

Mechanical Attachment

Contact Current Rating (Max)

| Connector Mounting Type | Board Mount |
|-------------------------|-------------|
|-------------------------|-------------|

1.1 A

30 µin



Housing Features

| Centerline (Pitch) | 1 mm[.039 in] |
|-----------------------------|---------------|
| Dimensions | |
| PCB Thickness (Accepted) | 1.57 mm |
| Usage Conditions | |
| Operating Temperature Range | -40 – 85 °C |
| Operation/Application | |
| Circuit Application | Signal |
| Industry Standards | |
| Bus Type | PCI Express |
| PCI Generation | 4 |
| Packaging Features | |
| Packaging Method | Box & Tray |

Product Compliance

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU | Compliant |
|---|---|
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Not reviewed for solder process capability |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides



on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Customers Also Bought















Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_5-2337939-3_A.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_5-2337939-3_A.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5-2337939-3_A.3d_stp.zip



English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Product Specification

English

Product Specification

English

Agency Approvals

UL Report

English